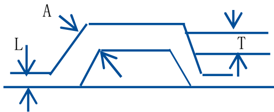
# ALLPCB

## MICROSECTION INSPECTION REPORT

1.Thickness Measurements of Copper, Solder, Solder Mask (Unit: um)

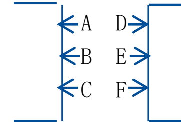
| Items | | Hole Wall Cu | | | | | | Solder Thickness | | Solder Mask | | |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | | A | B | C | D | E | F | Hole(avg.) | SMT | A | T | L |
| Requirement | | MI Requirment≥20um | | | | | | ≥1-40um | | ≥10 | ≥10 | ≥10 |
| Result | #1 | 21.5 | 23.7 | 22.0 | 21.0 | 23.2 | 22.8 | 6.25 | | 15.6 | 17.3 | 16.4 |
| | #2 | | | | | | | | | | | |
| | #2 | | | | | | | | | | | |
| | | | | | | | | | | | | |

Solder Mask




Specimen Locations

Hole Wall Cu,Solder




2.Thickness Measurement of Copper (Internal and Outter Layers) (Unit:um)

| Layer | | L1 | L2 | L3 | L4 | L5 | L6 | L7 | L8 | L9 | L10 | L11 | L12 |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Requirement | | / | / | / | / | / | / | / | / | / | / | / | / |
| Result | #1 | / | / | / | / | / | / | / | / | / | / | / | / |
| | #2 | / | / | / | / | / | / | / | / | / | / | / | / |

3. Measurements of Drilling Roughness and Dielectric Thickness (Unit: mm)

| Item | | Roughness | Dielectric Thickness | | | | | |
|---|---|---|---|---|---|---|---|---|
| | Requirement | ≤25.4 | | / | / | | | |
| Result | #1 | 15.60 | | | / | | | |
| | #2 | 17.30 | | | | | | |
| | #3 | 16.80 | | | | | | |

4. Defects Inspection

| Item | Pass | Fail |
|---|---|---|
| Smear | ACC | |
| Plating Void | ACC | |
| Plating Crack | ACC | |
| Burrs and Nodules | ACC | |
| Glass Fiber Protrusion | ACC | |
| Pad Lifted Land | ACC | |
| Separation Between Layers | ACC | |
| Pull Away of Hole Copper | ACC | |
| Connection Separation Between internal Layer | ACC | |

**Remarks:**

**Disposition:** ◆ACC RE◇

QA Inspected By: 鲁世蓓 QA Approved By: 付家贵